QUARTERLY PROGRESS REPORT

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RF VACUUM MICROELECTRONICS ARPA ORDER NO. <u>8162</u>

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RF Vacuum Microelectronics Quarterly Progress Report Number 2			C MDA972-91-C-0032	
6. AUTHOR(S)			1	
Dr. Alan Palevsky				
7. PERFORMING ORGANIZATION NAME(S) AND	ADDRESS(ES)	<u>-</u>	8. PERFORMING ORGANIZATION REPORT NUMBER	
Raytheon Company Research Division 131 Spring Street			RAY/RD/S-4752	
Lexington, MA 02172				
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microelectronics is present	development on field emissied. The dc emission character plete and are being fabricate	cteristics have improv	or RF vacuum ved. Designs for high	
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Field Emission, Vacuum Tubes, Cathodes			5 16. PRICE CODE	
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CONTRACT NO: MDA972-91-C-0032
CONTR. TITLE: RF VACUUM MICROELECTRONICS
CONTRACTOR: RAYTHEON CO., RESEARCH DIV.

DATE PREPARED: REPORT PERIOD:

04-Mer-92 01/27/92-02/23/92

FUNDS AND MANHOUR EXPENDITURE REPORT

CONTRACT VALUE:	\$1,095,328
CURRENT FUNDING (sell):	\$762,000
NEG. FEE RATE:	0.0%

	CONTRACT VALUE	REPORTING MO. EXPEN- DITURES	CUMULATIVE EXPEND. TO DATE	% \$ VALUE	COST TO COMPLETE ESTIMATE	LATEST COST ESTIMATE	PREVIOUS COST ESTIMATE
A	B	C	D	E	F	G	Н
TOTAL PRIME LABOR HOURS	7,467	292	1,420	- 12 2 2 2 2 2 2 2 2 2	6,047	7,467	
TOTAL PRIME LABOR	\$203,891	\$8,581	\$42,772		\$161,119	\$203,891	0
LABOR OVERHEAD	\$362,926	\$14,929	\$75,792		\$287,134	\$362,926	0
TOTAL LABOR & OVERHEAD	\$566,817	\$23,510	\$118,564		\$448,253	\$566,817	0
MATERIALS	\$220,841	\$5,128	\$6,880		\$213,961	\$220,841	0
ODC	\$830	\$76	\$428		\$402	\$830	0
WR	\$135,944	\$4,302	\$7,934		\$128,010	\$135,944	0
PRODUCT COST	\$924,432	\$33,016	\$133,806		\$790,626	\$924,432	0
G & A	\$148,407	\$5,255	\$22,046		\$126,361	\$148,407	0
СОМ	\$22,489	(\$1,349)	\$2,870		\$19,619	\$22,489	0
TOTAL COST LEVEL	\$1,095,328	\$36,922	\$158,722		\$936,606	\$1,095,328	0
FEE	\$0	\$0	\$0		\$0	\$0	0
TOTAL CONTRACT PRICE	\$1,095,328	\$36,922	\$158,722	14.49%	\$936,606	\$1,095,328	0
OUTSTANDING COMMIT		\$113,472	\$113,472				
TOTAL COMMIT & EXPEND.	\$1,095,328	\$150,394	\$ 272,194	24.85%	\$936,606	\$1,095,328	0
					:		

EXPENDITURES THIS QUARTER: \$101,907 TOTAL EXPENDITURES TO DATE: \$158,722 PROJECTED EXPENDITURES: 01/92 - 03/92: \$160,500 04/92 - 06/92: 07/92 - 09/92: \$175,000 Seese 94 on For \$198,400 10/92 - 12/92: \$215,100 NTIS URLAI BY40 TAB **TOTAL FY92 EXPENDITURES:** \$692,622 Manage and the second 1) IS CURRENT FUNDING SUFFICIENT (Y/N): YES Justification 2) WHAT IS FY93's FUNDING REQUIRMENT?: \$1,095,328 By_ 3) IS ALL DATA CROSS REFERENCED?: YES Distribution Availability Codes Asail and/or Special Dist



QUARTERLY PROGRESS REPORT NO. 2

1/2/92 - 3/31/92

Sponsored By: Dr. Bertram Hui

DARPA/DSO

3701 N. Fairfax Drive Arlington, VA 22203 Tel: (703) 696-2239

Monitored By:

Contractor: Raytheon Company

Research Division
131 Spring Street

Lexington, MA 02173

Effective Date of Contract: September 18, 1991

Contract Expiration Date: March 15, 1993

Contract Amount - Basic : \$1,095,328

- Options: \$ 640,090

Principal Investigator: Dr. Alan Palevsky

Tel: (617) 860-3036

FAX: (617) 860-3195

Title of Work: Research on RF Vacuum Microelectronics

y I. EXECUTIVE SUMMARY

Raytheon

VHF micro-triode (cylindrical) design complete

VHF micro-triode machined parts and masks ordered

Initial design for planar triode complete

Flanges for planar triode ordered

Series resistor process development started

Achieved 10uA/tip emission

Cornell

Fabricated 400 element arrays with dimpled grid structure

Performed initial test to verify a.c. (10kHz) and d.c. emission from arrays. 100 volt turn on voltage.

Fabricated package to demonstrate Rf modulation of the structures.

II. MILESTONES STATUS	Completion Date		
	Original		
1. Tip Field Emitter	•		
1.1 Process enhancement	2/93		
1.2 Leakage current suppression	7/92	4/92	
1.3 Series resistor development	9/92		
1.4 Alternative Emitter materials	2/93		
2. Wing Field Emitter			
2.1 Process development	4/92		
2.2 Electrical tests	6/92		
3. DC/Low Frequency Test			
3.1 Improve bakeout and turn on proc.	12/91	12/91	
3.2 Life tests	2/93		
4. High Frequency Design			
4.1 VHF micro-triode (cylindrical)	5/92		
design/fab			
4.2 Planar micro-triode design/fab	5/92		
5. High Frequency Test			
5.1 Test VHF micro-triode	8/92		
5.2 Test planar micro-triode	8/92		

III. TECHNICAL PROGRESS

Raytheon

- 1.1 A set of wafers were processed with only a small number of single tip as opposed to large arrays. This let us examine variations among single tips as opposed to ensemble averages. We found the variations in gate voltage for a given current to be as great as thirty volts. This indicates that probably only a small number of tips are providing all the current in the large arrays.
- 1.3 It also shows the need for a good ballast resistor to limit the current from the lower gate voltage tips. A process to add a series resistance to each tip is under development.
- 1.4 Studies of alternative emitter materials have started. 1000 angstroms of hafnium was put down on moly tips but electrical tests show no improvement. We are now looking at metal carbides which are refractory and are supposed to have a low work function. A novel deposition scheme will be used for these materials.

4.1 - 2

The design of the both high frequencies triodes was completed. All the ceramic and metal parts for the VHF micro-triode were ordered. The masks for fabrication of the emitter for the triode were layed out and ordered. Processing of wafers for this triode should start at the end of April. The masks for the planar triode are currently in layout. The high frequency, bakable to 450 degrees centigrade, vacuum coaxial lines and feedthru's needed for this circuit are waiting for vendor pricing. The base flanges on which the high frequency lines attach to is already on order. All the test equipment needed to test these two types of triodes will be procured before chips are available and therefore should not be a gating item.

The new evaporator (purchased with internal funds) should be ready to use in the July time frame. This should reduce our processing time from six weeks to four weeks.

IV. FISCAL STATUS

V. PROBLEM AREAS

No electrical performance has been obtained from the wing (circular edge emitters. We will probably stop all contract work on this style of emitter next quarter.

VI. VISITS AND TECHNICAL PRESENTATIONS

Both Raytheon and Cornell presented at the first Semi-Annual review with all the other contractors.